

10/706624

Examiner: PASCHALL, MARK

GAU: 3742

Classification: 219/121.430


Inventor: SHIMIZU, AKIRA, et al

Status: 30 - DOCKETED NEW CASE - READY FOR EXAMINATION

Title: METHOD FOR SEMICONDUCTOR WAFER ETCHING

Bib Data report

**Application Title:** METHOD FOR SEMICONDUCTOR WAFER ETCHING

**Application Num:**  (in phx) 10706624 **Filing Date:** 11/12/2003

**Effective Filing:** 11/12/2003

(Location History) (Foreign/Continuity Data)

**Status:** 30/DOCKETED NEW CASE - READY FOR EXAMINATION **Status Date:** 08/03/2004

**Patent Number:** Not Issued **Issue Date:** N/A **Date of Abandonment:** N/A  
**Confirmation Number:** 7986 **PALM Location:**

**Examiner:** 61092 PASCHALL, MARK (Assignment Data) **Group Art Unit:** 3742  
**Class/Subclass:** 219/121.430

**State or Country:** JAPAN **Sheets/Drawing:** 1 **Total Claims:** 17  
**Independent Claims:** 3

☒ **Inventors:**

Last name, First name:	City:	Country or State:
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SHIMIZU, AKIRA	TOKYO	JAPAN
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NANBA, KUNITOSHI	TOKYO	JAPAN
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**Attorneys:** ALL **Attorney Docket No:** ASMJP\_104DV1

**Interference No:** **Lost Case No:** **Unmatched Petition No:** **L&R Code:** 1



## UNITED STATES PATENT AND TRADEMARK OFFICE

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## \*BIBDATASHEET\*

CONFIRMATION NO. 7986

Bib Data Sheet

SERIAL NUMBER 10/706,624	FILING DATE 11/12/2003  RULE	CLASS 219	GROUP ART UNIT 3742	ATTORNEY DOCKET NO. ASMJP.104DV1
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## APPLICANTS

Akira Shimizu, Tokyo, JAPAN;

Kunitoshi Nanba, Tokyo, JAPAN;

## \*\* CONTINUING DATA \*\*

This application is a DIV of 10/068,092 02/05/2002 PAT 6,764,572 OK.

## \*\* FOREIGN APPLICATIONS \*\*

JAPAN 2001-056685 03/01/2001

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 02/20/2004

Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged Examiner's Signature: <i>[Signature]</i> Initials: <i>mn</i>	JAPAN	1	17	3

## ADDRESS

20995  
KNOBBE MARTENS OLSON & BEAR LLP  
2040 MAIN STREET  
FOURTEENTH FLOOR  
IRVINE, CA  
92614

## TITLE

Method for semiconductor wafer etching

FILING FEE	FEES: Authority has been given in Paper	<input type="checkbox"/> All Fees
RECEIVED	No. _____ to charge/credit DEPOSIT ACCOUNT	<input type="checkbox"/> 1.16 Fees ( Filing )
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